



DEVICE TYPE:				SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006				
CUSTOMER:		DIE SIZE:						
WIRE TYPE/ SIZE:		NO. OF WIRES:						
THIRD ANGLE PROJECTION UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING	REVISIONS					16 Lead 3mm x 3mm MLP Open-Pak Bonding Diagram		
	ECN NO.	DATE	DESCRIPTION	APPROVED				
	10657	6/16/06	PRODUCTION RELEASE	D.BENANDO				
DRAWN BY	R. ALCORN	DATE	6/16/06	PACKAGE SIZE:	3.00mm x 3.00mm	SIZE	PART NO.	REV
APP BY	P. FLASKERUD	DATE	6/16/06	DIE PAD SIZE:	1.36mm x 1.36mm	A	MLP3X3-16-OP-01	1
						SCALE	CAD FILE	SHEET
						50X	MLP3X3-12-OP-01-B-R1.DWG	1 OF 1